

	Hits	Search Text	DBs	Time Stamp
1	2	(substrates and (stack stacking stacked) and circuits and (removing remove removed etch etching etched) and (bond bonding bonded adhesive) and flexible).clm.	US-PGPUB; USPAT	2006/09/25 15:06
2	0	(substrates and (stack stacking stacked) and circuits and (removing remove removed etch etching etched) and (bond bonding bonded adhesive) and flexible).clm.	US-PGPUB	2006/09/25 15:06
3	17	(substrates and (stack stacking stacked) and (removing remove removed etch etching etched) and (bond bonding bonded adhesive) and flexible).clm.	US-PGPUB	2006/09/25 15:06
4	11	(substrates and (stack stacking stacked) and (removing remove removed etch etching etched) with (substrate substrates) and (bond bonding bonded adhesive) and flexible).clm.	US-PGPUB	2006/09/25 15:07
5	8	(substrates and (stack stacking stacked) and (removing remove removed etch etching etched) with (substrate substrates) and (bond bonding bonded adhesive) and flexible with (substrate substrates)).clm.	US-PGPUB	2006/09/25 15:09
6	10	(substrates and (stack stacking stacked) and memory and (bond bonding bonded adhesive) and flexible with (substrate substrates)).clm.	US-PGPUB	2006/09/25 15:10
7	9	(substrates and (stack stacking stacked) and memory and (bond bonding bonded adhesive) and flexible with (substrate substrates) and data).clm.	US-PGPUB	2006/09/25 15:10
8	9	(substrates and (stack stacking stacked) and memory and (bond bonding bonded adhesive) and flexible with (substrate substrates) and data and (defect defective)).clm.	US-PGPUB	2006/09/25 15:10

	Hits	Search Text	DBs	Time Stamp
9	9	(substrates and (stack stacking stacked) and memory and (bond bonding bonded adhesive) and flexible with (substrate substrates) and data and (defect defective) with memory).clm.	US-PGPUB	2006/09/25 15:12
10	0	(substrates and (stack stacking stacked) and (bond bonding bonded adhesive) and flexible with (substrate substrates) and reconfiguration).clm.	US-PGPUB	2006/09/25 15:11
11	0	(substrates and (stack stacking stacked) and flexible with (substrate substrates) and reconfiguration).clm.	US-PGPUB	2006/09/25 15:11
12	0	(substrates and flexible with (substrate substrates) and reconfiguration).clm.	US-PGPUB	2006/09/25 15:11
13	9	(substrates and (stack stacking stacked) and memory and (bond bonding bonded adhesive) and flexible with (substrate substrates) and data and storage).clm.	US-PGPUB	2006/09/25 15:12
14	9	(substrates and (stack stacking stacked) and memory and (bond bonding bonded adhesive) and flexible with (substrate substrates) and data and storage and controller).clm.	US-PGPUB	2006/09/25 15:13
15	9	(substrates and (stack stacking stacked) and memory and (bond bonding bonded adhesive) and flexible with (substrate substrates) and data and storage with memory and controller).clm.	US-PGPUB	2006/09/25 15:13